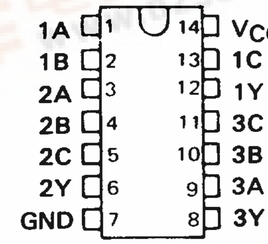
SN5410, SN54LS10, SN54S10, SN7410, SN74LS10, SN74S10 TRIPLE 3-INPUT POSITIVE-NAND GATES

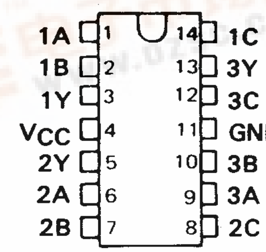
SDLS035A – DECEMBER 1983 – REVISED APRIL 2003

- **Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs**
- **Dependable Texas Instruments Quality and Reliability**

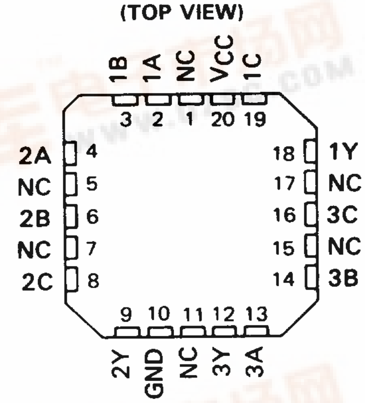
SN5410 . . . J PACKAGE
SN54LS10, SN54S10 . . . J OR W PACKAGE
SN7410 . . . N PACKAGE
SN74LS10, SN74S10 . . . D OR N PACKAGE
(TOP VIEW)



SN5410 . . . W PACKAGE
(TOP VIEW)



SN54LS10, SN54S10 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

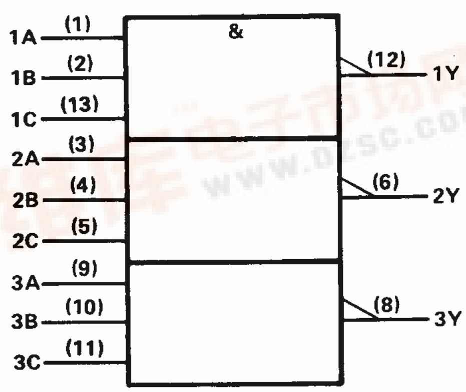
These devices contain three independent 3-input NAND gates.

The SN5410, SN54LS10, and SN54S10 are characterized for operation over the full military temperature range of −55°C to 125°C. The SN7410, SN74LS10, and SN74S10 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

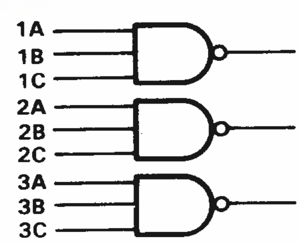
INPUTS			OUTPUT
A	B	C	Y
H	H	H	L
L	X	X	H
X	L	X	H
X	X	L	H

logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, and N packages.

logic diagram (positive logic)

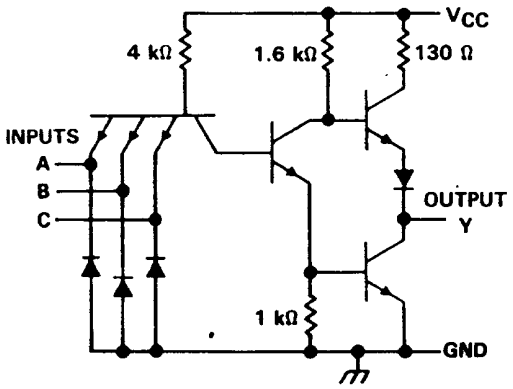


positive logic

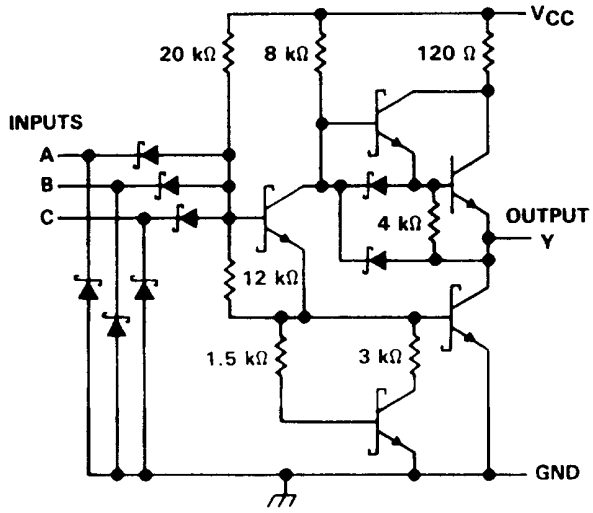
$$Y = \overline{A \cdot B \cdot C} \text{ or } Y = \overline{A} + \overline{B} + \overline{C}$$

schematics (each gate)

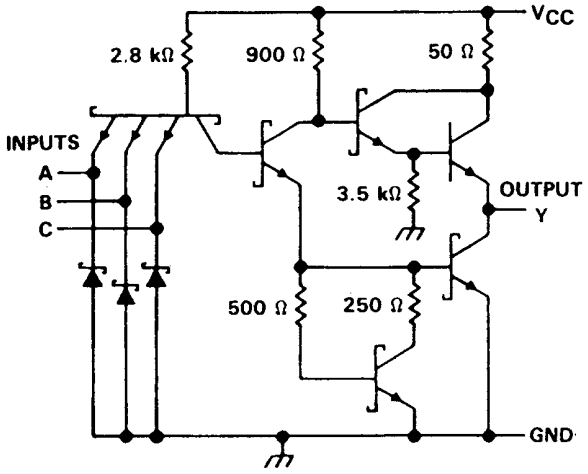
'10



'LS10



'S10



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)		7 V
Input voltage: '10, 'S10		5.5 V
'LS10		7 V
Operating free-air temperature range: SN54'		−55°C to 125°C
SN74'		0°C to 70°C
Storage temperature range		−65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN5410			SN7410			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.8			0.8	V
I_{OH} High-level output current			– 0.4			– 0.4	mA
I_{OL} Low-level output current			16			16	mA
T_A Operating free-air temperature	– 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †	SN5410			SN7410			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = – 12 mA			– 1.5			– 1.5	V
V_{OH}	V_{CC} = MIN, V_{IL} = 0.8 V, I_{OH} = – 0.4 mA	2.4	3.4		2.4	3.4		V
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I_I	V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.4 V			40			40	μA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V			– 1.6			– 1.6	mA
I_{OS}§	V_{CC} = MAX	– 20		– 55	– 18		– 55	mA
I_{CCH}	V_{CC} = MAX, V_I = 0 V		3	6		3	6	mA
I_{CCL}	V_{CC} = MAX, V_I = 4.5 V		9	16.5		9	16.5	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A, B or C	Y	R_L = 400 Ω, C_L = 15 pF		11	22	ns
t_{PHL}					7	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

	SN54LS10			SN74LS10			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.7			0.8	V
I_{OH} High-level output current			– 0.4			– 0.4	mA
I_{OL} Low-level output current			4			8	mA
T_A Operating free-air temperature	– 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †			SN54LS10			SN74LS10			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN,	I_I = – 18 mA				– 1.5			– 1.5	V
V_{OH}	V_{CC} = MIN,	V_{IL} = MAX,	I_{OH} = – 0.4 mA	2.5	3.4		2.7	3.4		V
V_{OL}	V_{CC} = MIN,	V_{IH} = 2 V,	I_{OL} = 4 mA		0.25	0.4			0.4	V
	V_{CC} = MIN,	V_{IH} = 2 V,	I_{OL} = 8 mA					0.25	0.5	
I_I	V_{CC} = MAX,	V_I = 7 V				0.1			0.1	mA
I_{IH}	V_{CC} = MAX,	V_I = 2.7 V				20			20	μA
I_{IL}	V_{CC} = MAX,	V_I = 0.4 V				– 0.4			– 0.4	mA
I_{OS}§	V_{CC} = MAX			– 20		– 100	– 20		– 100	mA
I_{CCH}	V_{CC} = MAX,	V_I = 0 V			0.6	1.2		0.6	1.2	mA
I_{CCL}	V_{CC} = MAX,	V_I = 4.5 V			1.8	3.3		1.8	3.3	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A, B or C	Y	R_L = 2 kΩ, C_L = 15 pF		9	15	ns
t_{PHL}					10	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

	SN54S10			SN74S10			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.8			0.8	V
I_{OH} High-level output current			−1			−1	mA
I_{OL} Low-level output current			20			20	mA
T_A Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †	SN54S10			SN74S10			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = −18 mA			−1.2			−1.2	V
V_{OH}	V_{CC} = MIN, V_{IL} = 0.8 V, I_{OH} = −1 mA	2.5	3.4		2.7	3.4		V
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 20 mA			0.5			0.5	V
I_I	V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.7 V			50			50	μA
I_{IL}	V_{CC} = MAX, V_I = 0.5 V			−2			−2	mA
I_{OS}§	V_{CC} = MAX	−40		−100	−40		−100	mA
I_{CCH}	V_{CC} = MAX, V_I = 0 V		7.5	12		7.5	12	mA
I_{CCL}	V_{CC} = MAX, V_I = 4.5 V		15	27		15	27	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A, B or C	Y	R_L = 280 Ω, C_L = 15 pF		3	4.5	ns
t_{PHL}					3	5	ns
t_{PLH}			R_L = 280 Ω, C_L = 50 pF		4.5		ns
t_{PHL}					5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
JM38510/00103BCA	OBSOLETE	CDIP	J	14		None	Call TI	Call TI
JM38510/00103BDA	OBSOLETE	CFP	W	14		None	Call TI	Call TI
JM38510/07005BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/07005BDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005B2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
JM38510/30005BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005BDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005SCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005SDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SN5410J	OBSOLETE	CDIP	J	14		None	Call TI	Call TI
SN54LS10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN54S10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN7410N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7410N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74LS10D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LS10DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LS10N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS10N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74LS10NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74S10D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74S10N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S10N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74S10NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ5410J	OBSOLETE	CDIP	J	14		None	Call TI	Call TI
SNJ5410W	OBSOLETE	CFP	W	14		None	Call TI	Call TI
SNJ5410WA	OBSOLETE	CFP	WA	14		None	Call TI	Call TI
SNJ54LS10FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54LS10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54LS10W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SNJ54S10FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54S10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54S10W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

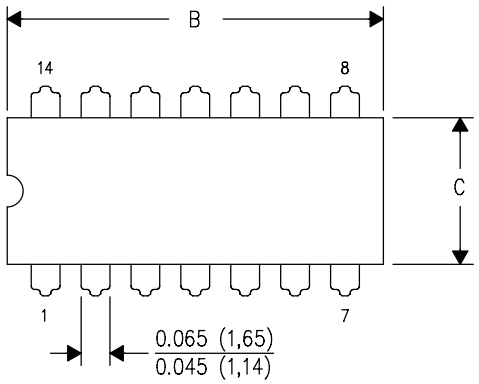
(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
None: Not yet available Lead (Pb-Free).
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

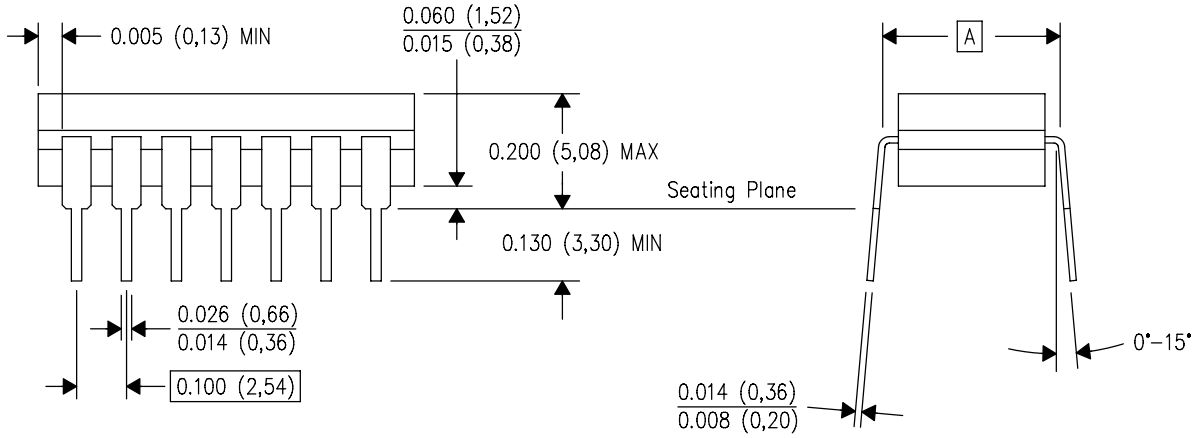
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



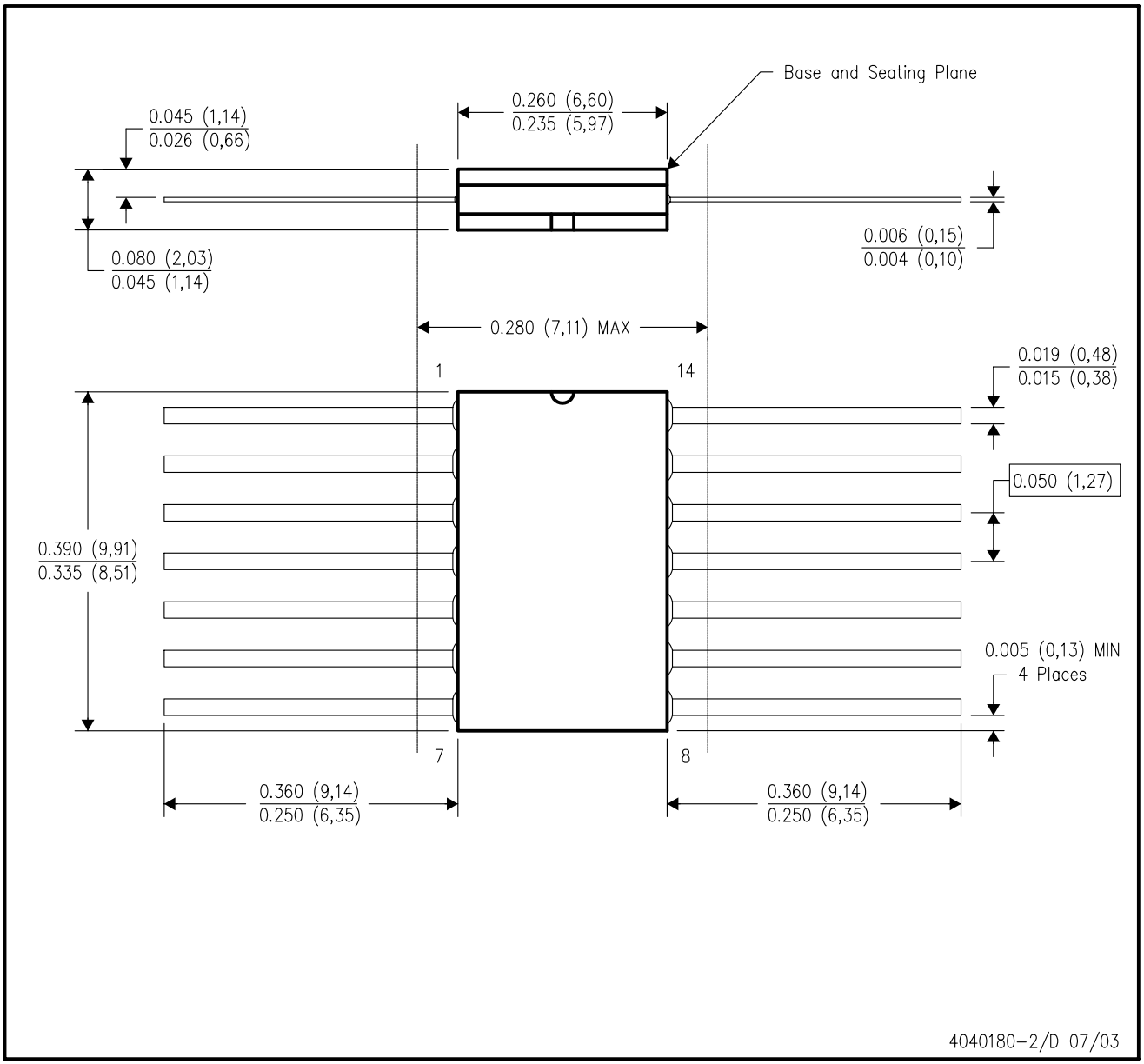
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

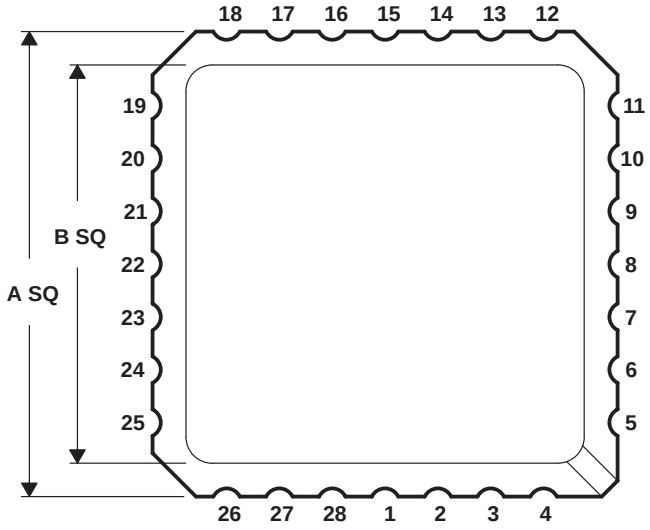
W (R–GDFP–F14) CERAMIC DUAL FLATPACK



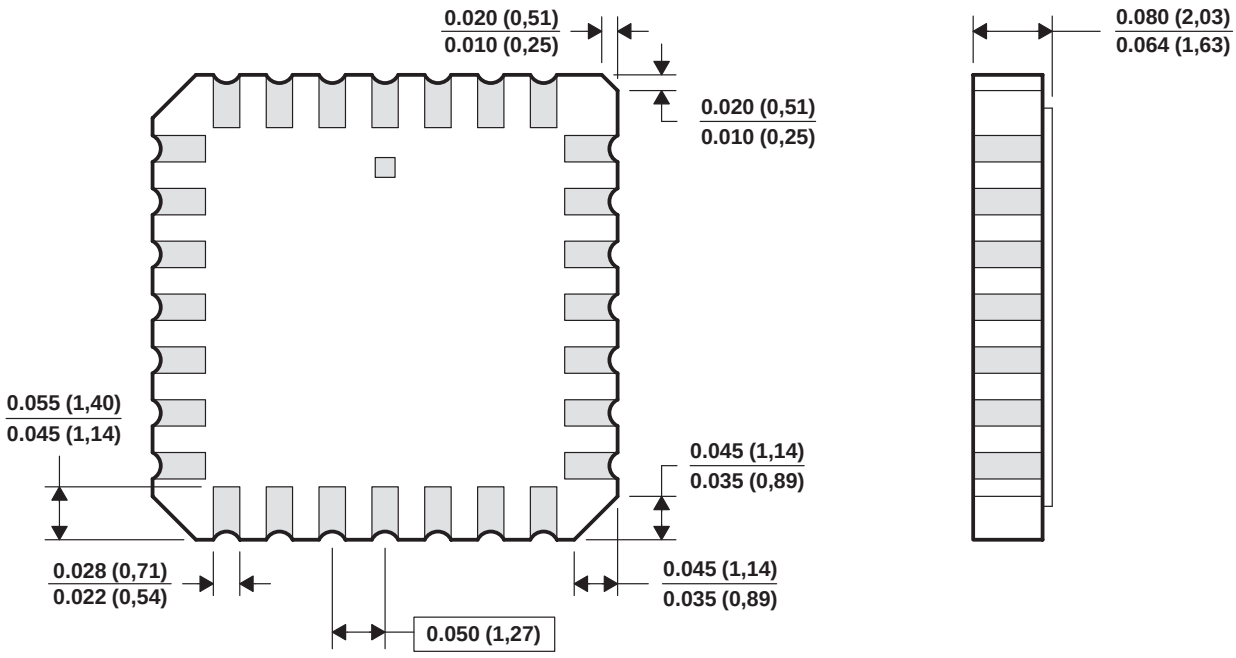
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



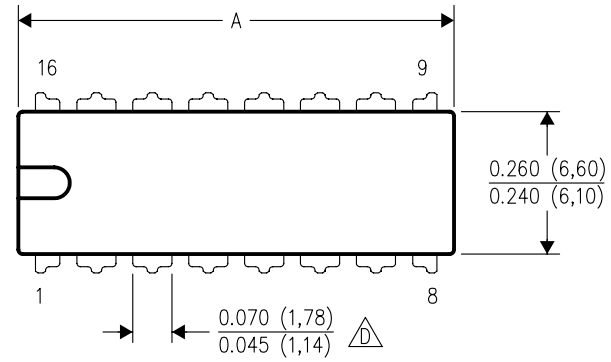
4040140/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

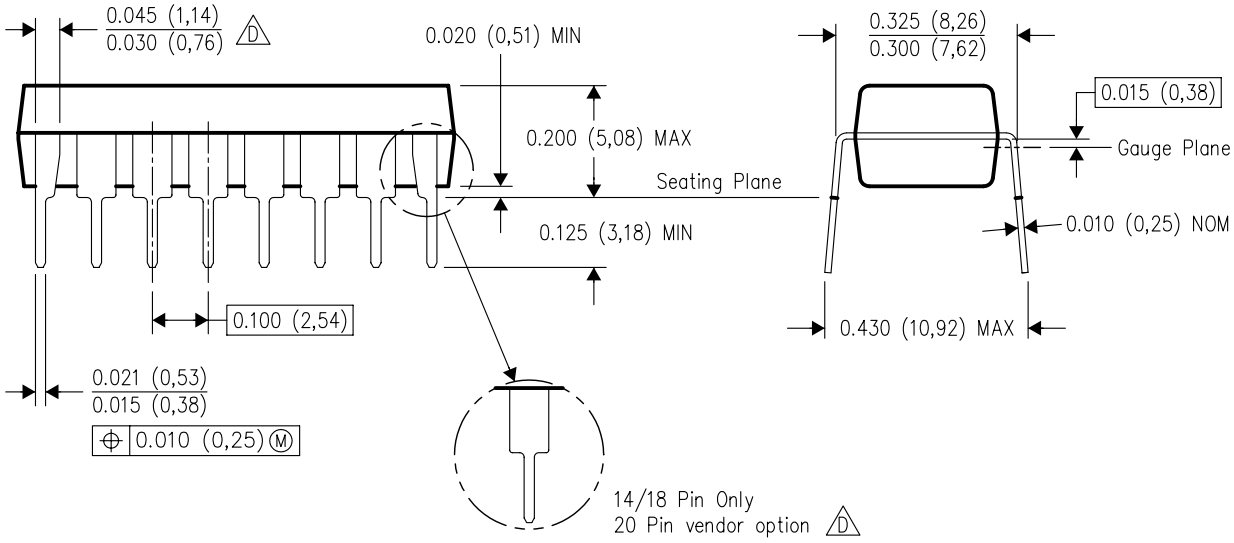
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



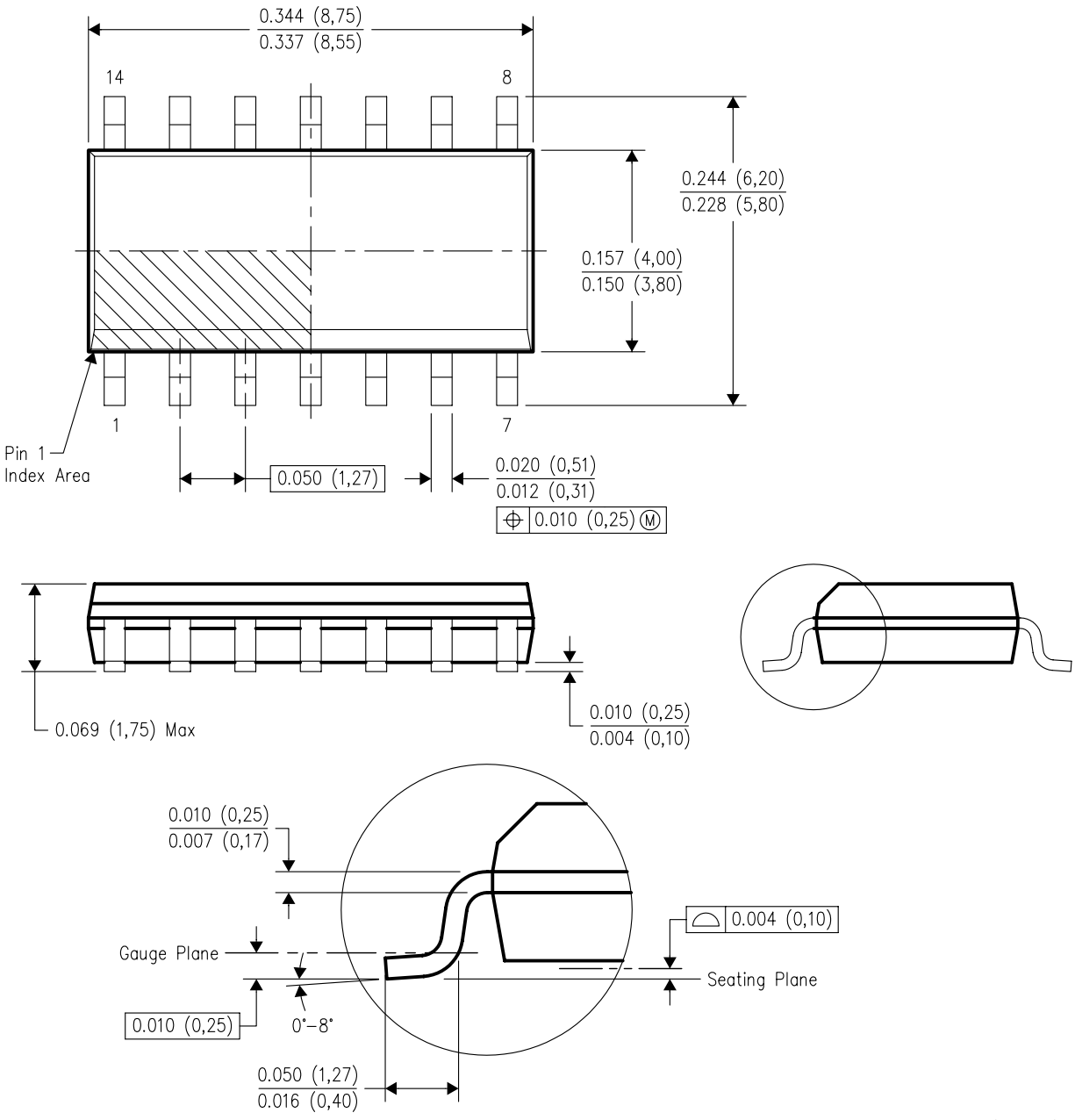
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G14) PLASTIC SMALL–OUTLINE PACKAGE

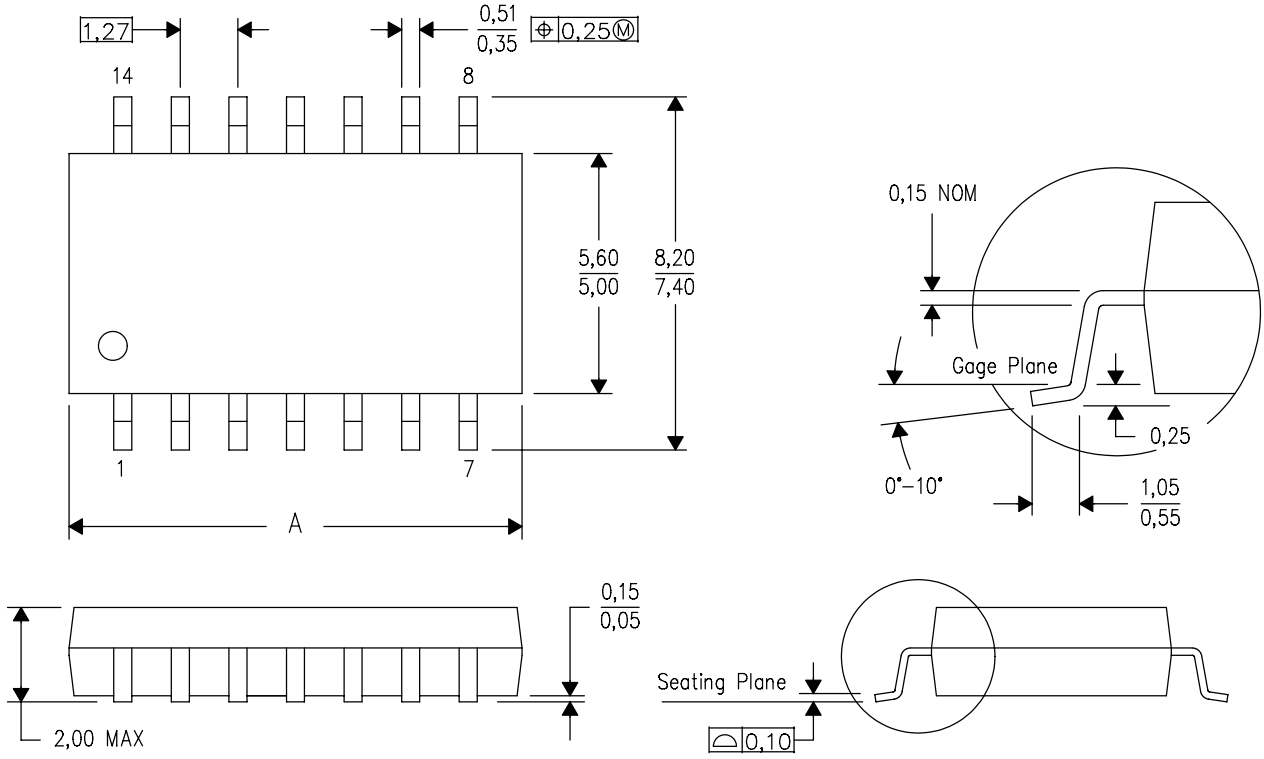


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AB.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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